



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



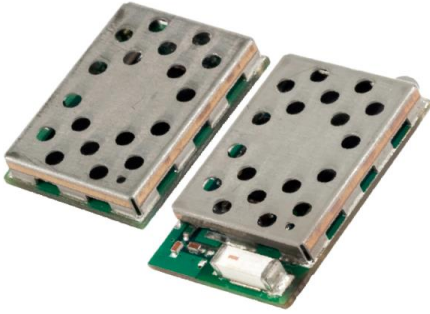
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The BTM410 and BTM411 Bluetooth® modules from Laird have been designed to meet the needs of developers who wish to add robust, short range Bluetooth data connectivity to their products. They are based on the market leading Cambridge Silicon Radio BC04 chipset, providing exceptionally low power consumption with outstanding range. They support the latest Bluetooth Version 2.1 Specification, providing the important advantage of Secure Simple Pairing, which improves security and enhances the ease of use for end customers.

With a footprint as small as 12.5 mm x 18.0 mm for the BTM410 and best of class, low-power operation, these modules are the ideal choice for applications where designers need both performance and minimum size. For maximum flexibility in systems integration, the modules are designed to support a separate power supply for I/O.

To aid product development and integration, Laird has integrated a complete Bluetooth protocol stack within the modules, including support for the Bluetooth Serial Port Profile. The modules are fully qualified as Bluetooth End Products, allowing designers to integrate them within their own products with no further Bluetooth Qualification.

A comprehensive AT command interface is included, which simplifies firmware integration. Combined with a low cost developer's kit, this ensures that choosing Laird Bluetooth modules guarantees the fastest route to market.

Features and Benefits

- Bluetooth v2.1+EDR
- Adaptive frequency hopping to cope with interference from other wireless devices
- Secure Simple Pairing support
- External or internal antenna options
- Comprehensive AT interface for simple programming
- Bluetooth End Product Qualified
- Compact size
- Class 2 output – 4 dBm
- Low power operation
- UART interface
- PCM and SCO for external codec
- GPIO lines under AT control
- Wi-Fi co-existence

Application Areas

- Embedded devices
- Phone accessories
- Security devices
- Medical and telehealth devices
- Aftermarket automotive applications
- Bluetooth advertising
- ePOS

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CATEGORIES	FEATURE	IMPLEMENTATION
Wireless Specification	Bluetooth®	Version 2.1+EDR
	Frequency	2.402 – 2.480 GHz
	Max Transmit Power	Class 2 +4 dBm (at antenna pad – BTM410) +4 dBm (from integrated antenna – BTM411)
	Receive Sensitivity	Better than -84 dBm
	Range	Up to 30 meters
	Data Rates	Up to 2.1 Mbps (over the air)
	UART Data Transfer Rate	Greater than 300 Kbps
Host Interface	UART	Supports CTS, RTS, DRT, DSR, DCD and RI
User Interface	GPIO	8 lines (shared)
Profiles		SPP – Serial Port Profile Voice over SCO via a PCM interface
Supply Voltage	Supply	3.0 V to +3.3 V
	I/O	1.7 V to +3.6 V (independent of VCC)
Power Consumption	Current Consumption	Less than 40 mA during SCO transmission Idle (sleep) < 1 mA
	Coexistence / Compatibility	802.11 (Wi-Fi)
Connections	External Antenna	Connection via SMT pad – BTM410
	Internal Antenna	Multilayer ceramic – BTM411
Protocols		AT Command Set
Physical	Dimensions	12.5 mm x 18.0 mm x 3.4 mm (external antenna – BTM410)
		12.5 mm x 22.0mm x 3.4 mm (integrated antenna – BTM411)
Environmental	Operating Temperature	-40° C to +85° C
	Storage Temperature	-40° C to +85° C
Miscellaneous	Lead Free	Lead-free and RoHS compliant
	Warranty	1-Year Warranty
Developmental Tools	Development Kit	Development board and software tools
Approvals	Bluetooth	End Product Approved
	FCC/IC & CE	BTM410 – Limited Modular Approval BTM411 – Full Modular Approval

Ordering Information

BTM410	Bluetooth AT Data Module (external antenna)
BTM411	Bluetooth AT Data Module (with integrated antenna)
DVK-BTM410	Development Kit (external antenna)
DVK-BTM411	Development Kit (with integrated antenna)

The details contained within the document are subject to change. Download the product specification from www.lairdtech.com/wireless for the most current specification.

CONN-DS-BTM410-411 v1.0

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Revision History

Version	Date	Changes	Approved By
1.0	02 Mar 13	Initial	J. Kaye